Electronic Patent Application Fee Transmittal							
Application Number:	10	10723096					
Filing Date:	26-Nov-2003						
Title of Invention:	MOLDING COMPOUND						
First Named Inventor/Applicant Name:	John E. Kendall						
Filer:	Scott Chapple/Elise Nichols						
Attorney Docket Number:	62806A (1062-023)						
Filed as Large Entity							
Utility Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
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Utility Appl Issue fee		1501	1	1400	1400		

Publ. Fee- early, voluntary, or normal

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